OUT1

OUT2

GND

DB7

DB6

DB5

DB4

DB3

GND

DB7

NC

DB6

DB5

2

3

4

5

6

7

8

OUT OUT NC RFB REF

5

6

7

8

ğ

NC-No internal connection

2 1

10 11

SLAS061C – SEPTEMBER 1986 – REVISED NOVEMBER 1998 D. N. OR PW PACKAGE

(TOP VIEW)

16

14

13

11

9

20 19

18 L

17

16

15

14

13

<u>B</u>

DB3 NC DB2 V_{DD}

WR

NC

CS

DB0

FN PACKAGE (TOP VIEW)

12

R_{FB}

V_{DD}

WR

CS

1 DB0

DB2

10 DB1

15 REF

- Easily Interfaced to Microprocessors
- On-Chip Data Latches
- Monotonic Over the Entire A/D Conversion Range
- Segmented High-Order Bits Ensure Low-Glitch Output
- Interchangeable With Analog Devices AD7524, PMI PM-7524, and Micro Power Systems MP7524
- Fast Control Signaling for Digital Signal-Processor Applications Including Interface With TMS320
- CMOS Technology

KEY PERFORMANCE SPECIFICATIONS					
Resolution	8 Bits				
Linearity error	1/2 LSB Max				
Power dissipation at $V_{DD} = 5 V$	5 mW Max				
Setting time	100 ns Max				
Propagation delay time	80 ns Max				

description

The TLC7524C, TLC7524E, and TLC7524I are CMOS, 8-bit, digital-to-analog converters (DACs) designed for easy interface to most popular microprocessors.

The devices are 8-bit, multiplying DACs with input latches and load cycles similar to the write cycles of a random access memory. Segmenting the high-order bits minimizes glitches during changes in the most significant bits, which produce the highest glitch impulse. The devices provide accuracy to 1/2 LSB without the need for thin-film resistors or laser trimming, while dissipating less than 5 mW typically.

Featuring operation from a 5-V to 15-V single supply, these devices interface easily to most microprocessor buses or output ports. The 2- or 4-quadrant multiplying makes these devices an ideal choice for many microprocessor-controlled gain-setting and signal-control applications.

The TLC7524C is characterized for operation from 0°C to 70°C. The TLC7524I is characterized for operation from -25°C to 85°C. The TLC7524E is characterized for operation from -40°C to 85°C.

		PACKAGE						
TA	SMALL OUTLINE PLASTIC DIP (D)	PLASTIC CHIP CARRIER (FN)	PLASTIC DIP (N)	SMALL OUTLINE (PW)				
0°C to 70°C	TLC7524CD	TLC7524CFN	TLC7524CN	TLC7524CPW				
-25°C to 85°C	TLC7524ID	TLC7524IFN	TLC7524IN	TLC7524IPW				
-40°C to 85°C	TLC7524ED	TLC7524EFN	TLC7524EN	-				

AVAILABLE OPTIONS



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

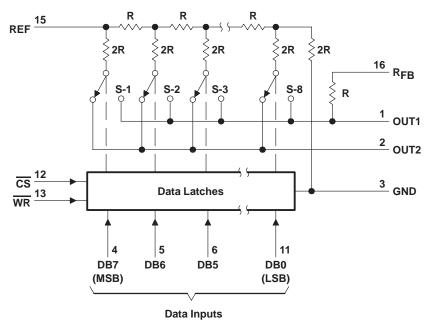
PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.



Copyright © 1998, Texas Instruments Incorporated

SLAS061C - SEPTEMBER 1986 - REVISED NOVEMBER 1998

functional block diagram



Terminal numbers shown are for the D or N package.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage range, V _{DD}		
Digital input voltage range, V ₁		$\dots -0.3 \text{ V to V}_{\text{DD}} + 0.3 \text{ V}$
Reference voltage, V _{ref}		±25 V
Peak digital input current, I		
Operating free-air temperature range, T _A :	TLC7524C	0°C to 70°C
	TLC7524I	–25°C to 85°C
	TLC7524E	–40°C to 85°C
Storage temperature range, T _{stg}		–65°C to 150°C
Case temperature for 10 seconds, T _C : FN		
Lead temperature 1,6 mm (1/16 inch) from		



SLAS061C - SEPTEMBER 1986 - REVISED NOVEMBER 1998

recommended operating conditions

			V _{DD} = 5 V V _{DD} = 15 V		V	UNIT			
			MIN	NOM	MAX	MIN	NOM	MAX	UNIT
Supply voltage, V _{DD}		4.75	5	5.25	14.5	15	15.5	V	
Reference voltage, Vref				±10			±10		V
High-level input voltage, VIH			2.4			13.5			V
Low-level input voltage, VIL				0.8			1.5	V	
CS setup time, t _{SU(CS)}		40			40			ns	
CS hold time, th(CS)			0			0			ns
Data bus input setup time, t _{SU(D)}			25			25			ns
Data bus input hold time, th(D)			10			10			ns
Pulse duration, WR low, t _{w(WR)}		40			40			ns	
	TLC7524C		0		70	0		70	
Operating free-air temperature, T _A	TLC7524I		-25		85	-25		85	°C
	TLC7524E		-40		85	-40		85	

electrical characteristics over recommended operating free-air temperature range, $V_{ref} = \pm 10$ V, OUT1 and OUT2 at GND (unless otherwise noted)

	PARAMETER		TEST CONDITIONS	V	DD = 5	V	٧ _D)D = 15	V	UNIT	
	PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	MIN	TYP	MAX	UNIT	
Iн	High-level input curre	nt	$V_I = V_{DD}$			10			10	μA	
١ _L	Low-level input currer	nt	$V_{I} = 0$			-10			-10	μA	
	Output leakage	OUT1	DB0–DB7 at 0 V, \overline{WR} , \overline{CS} at 0 V, $V_{ref} = \pm 10 V$			±400			±200	~^	
likg	likg current OUT2		DB0–DB7 at V _{DD} , \overline{WR} , \overline{CS} at 0 V, V _{ref} = ±10 V			±400			±200	- nA	
	Supply ourrept	Quiescent	DB0–DB7 at VIHmin or VILmax			1			2	mA	
IDD	Supply current	Standby	DB0–DB7 at 0 V or V _{DD}			500			500	μA	
ks∨s	Supply voltage sensit	vity,	$\Delta V_{DD} = \pm 10\%$		0.01	0.16		0.005	0.04	%FSR/%	
Ci	Input capacitance, DB0–DB7, WR, CS		V _I = 0			5			5	pF	
		OUT1				30			30		
		OUT2	DB0–DB7 at 0 V, WR, CS at 0 V		120			120	~ F		
Co	Output capacitance	OUT1				120			120	pF	
		OUT2	DB0–DB7 at V _{DD} , WR, CS at 0 V			30			30		
	Reference input impe (REF to GND)	dance		5		20	5		20	kΩ	



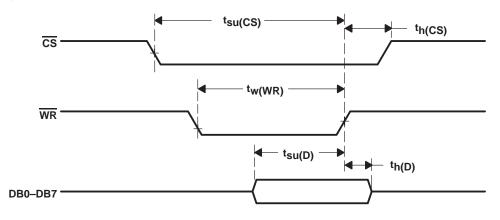
SLAS061C - SEPTEMBER 1986 - REVISED NOVEMBER 1998

operating characteristics over recommended operating free-air temperature range, $V_{ref} = \pm 10$ V, OUT1 and OUT2 at GND (unless otherwise noted)

DADAMETER	TEST CONDITIONS	V _{DD} = 5 V		V _{DD} = 15 V				
PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	MIN	TYP	MAX	UNIT
Linearity error				±0.5			±0.5	LSB
Gain error	See Note 1			±2.5			±2.5	LSB
Settling time (to 1/2 LSB)	See Note 2			100			100	ns
Propagation delay from digital input to 90% of final analog output current	See Note 2			80			80	ns
Feedthrough at OUT1 or OUT2	$\frac{Vref}{WR} = \pm 10 V (100 \text{-} kHz \text{ sinewave})$ WR and CS at 0 V, DB0–DB7 at 0 V	0.5		0.5			0.5	%FSR
Temperature coefficient of gain	$T_A = 25^{\circ}C$ to MAX		±0.004			±0.001		%FSR/°C

NOTES: 1. Gain error is measured using the internal feedback resistor. Nominal full-scale range (FSR) = V_{ref} - 1 LSB.
2. OUT1 load = 100 Ω, C_{ext} = 13 pF, WR at 0 V, CS at 0 V, DB0 - DB7 at 0 V to V_{DD} or V_{DD} to 0 V.

operating sequence





SLAS061C - SEPTEMBER 1986 - REVISED NOVEMBER 1998

PRINCIPLES OF OPERATION

voltage-mode operation

It is possible to operate the current-multiplying DAC in these devices in a voltage mode. In the voltage mode, a fixed voltage is placed on the current output terminal. The analog output voltage is then available at the reference voltage terminal. Figure 1 is an example of a current-multiplying DAC, which is operated in voltage mode.

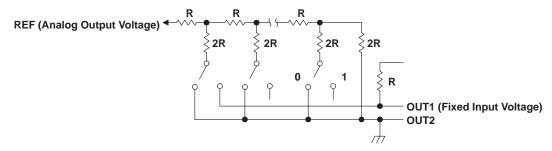


Figure 1. Voltage Mode Operation

The relationship between the fixed-input voltage and the analog-output voltage is given by the following equation:

$$V_{\rm O} = V_{\rm I} ({\rm D}/256)$$

where

 V_O = analog output voltage V_I = fixed input voltage D = digital input code converted to decimal

In voltage-mode operation, these devices meet the following specification:

PARAMETER	TEST CONDITIONS	MIN MAX	UNIT
Linearity error at REF	$V_{DD} = 5 \text{ V}, \text{OUT1} = 2.5 \text{ V}, \text{OUT2 at GND}, \text{T}_{A} = 25^{\circ}\text{C}$	1	LSB



SLAS061C - SEPTEMBER 1986 - REVISED NOVEMBER 1998

PRINCIPLES OF OPERATION

The TLC7524C, TLC7524E, and TLC7524I are 8-bit multiplying DACs consisting of an inverted R-2R ladder, analog switches, and data input latches. Binary-weighted currents are switched between the OUT1 and OUT2 bus lines, thus maintaining a constant current in each ladder leg independent of the switch state. The high-order bits are decoded. These decoded bits, through a modification in the R-2R ladder, control three equally-weighted current sources. Most applications only require the addition of an external operational amplifier and a voltage reference.

The equivalent circuit for all digital inputs low is seen in Figure 2. With all digital inputs low, the entire reference current, I_{ref} , is switched to OUT2. The current source I/256 represents the constant current flowing through the termination resistor of the R-2R ladder, while the current source I_{lkg} represents leakage currents to the substrate. The capacitances appearing at OUT1 and OUT2 are dependent upon the digital input code. With all digital inputs high, the off-state switch capacitance (30 pF maximum) appears at OUT2 and the on-state switch capacitance (120 pF maximum) appears at OUT1. With all digital inputs low, the situation is reversed as shown in Figure 2. Analysis of the circuit for all digital inputs high is similar to Figure 2; however, in this case, I_{ref} would be switched to OUT1.

The DAC on these devices interfaces to a microprocessor through the data bus and the \overline{CS} and \overline{WR} control signals. When \overline{CS} and \overline{WR} are both low, analog output on these devices responds to the data activity on the DB0–DB7 data bus inputs. In this mode, the input latches are transparent and input data directly affects the analog output. When either the \overline{CS} signal or \overline{WR} signal goes high, the data on the DB0–DB7 inputs are latched until the \overline{CS} and \overline{WR} signals go low again. When \overline{CS} is high, the data inputs are disabled regardless of the state of the \overline{WR} signal.

These devices are capable of performing 2-quadrant or full 4-quadrant multiplication. Circuit configurations for 2-quadrant or 4-quadrant multiplication are shown in Figure 3 and Figure 4. Table 1 and Table 2 summarize input coding for unipolar and bipolar operation respectively.

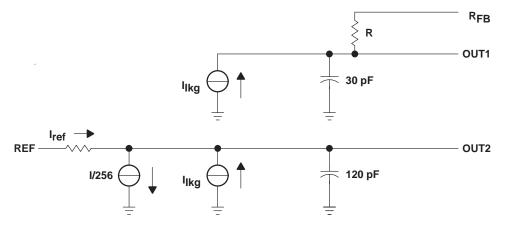
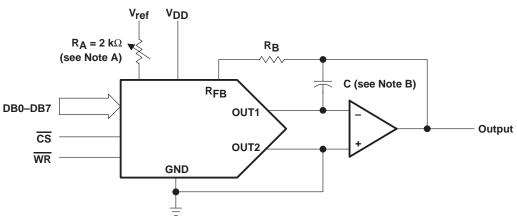


Figure 2. TLC7524 Equivalent Circuit With All Digital Inputs Low



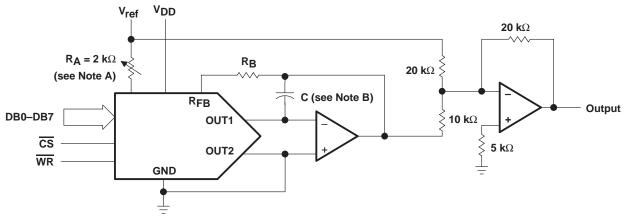
SLAS061C - SEPTEMBER 1986 - REVISED NOVEMBER 1998

PRINCIPLES OF OPERATION



NOTES: A. R_A and R_B used only if gain adjustment is required.
B. C phase compensation (10-15 pF) is required when using high-speed amplifiers to prevent ringing or oscillation.





NOTES: A. R_A and R_B used only if gain adjustment is required. B. C phase compensation (10-15 pF) is required when using high-speed amplifiers to prevent ringing or oscillation.

Figure 4. Bipola	Operation	(4-Quadrant	Operation)
------------------	-----------	-------------	--------------------

DIGITAL (see N		ANALOG OUTPUT
MSB	LSB	
1111	1111	-V _{ref} (255/256)
1000	0001	-V _{ref} (129/256)
1000	0000	$-V_{ref}$ (128/256) = $-V_{ref}/2$
0111	1111	-V _{ref} (127/256)
0000	0001	-V _{ref} (1/256)
0000	0000	0

Table	1.	Unipolar	Binary	Code
-------	----	----------	--------	------

NOTE 3: LSB = 1/256 (V_{ref})

Table 2. Bipolar (Offset Binary) Cod	е
--------------------------------------	---

DIGITAL (see N		ANALOG OUTPUT		
MSB	LSB			
1111	1111	V _{ref} (127/128)		
1000	0001	V _{ref} (1/128)		
1000	0000	0		
0111	1111	-V _{ref} (1/128)		
0000	0001	-V _{ref} (127/128)		
0000	0000	-V _{ref}		

NOTE 4: LSB = 1/128 (V_{ref})



SLAS061C - SEPTEMBER 1986 - REVISED NOVEMBER 1998

PRINCIPLES OF OPERATION

microprocessor interfaces

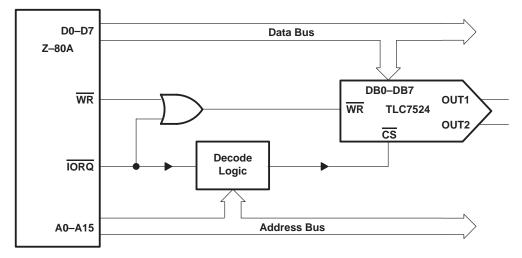


Figure 5. TLC7524 – Z-80A Interface

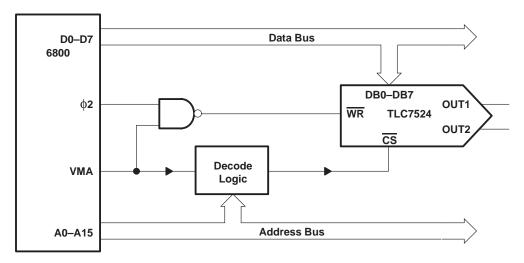


Figure 6. TLC7524 – 6800 Interface



SLAS061C - SEPTEMBER 1986 - REVISED NOVEMBER 1998

PRINCIPLES OF OPERATION



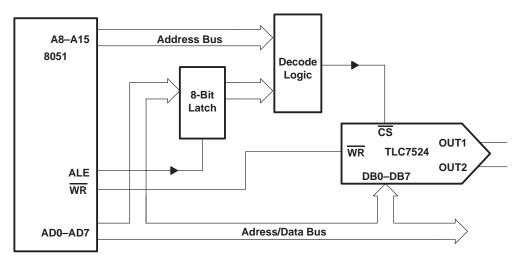


Figure 7. TLC7524 - 8051 Interface



IMPORTANT NOTICE

Texas Instruments and its subsidiaries (TI) reserve the right to make changes to their products or to discontinue any product or service without notice, and advise customers to obtain the latest version of relevant information to verify, before placing orders, that information being relied on is current and complete. All products are sold subject to the terms and conditions of sale supplied at the time of order acknowledgement, including those pertaining to warranty, patent infringement, and limitation of liability.

TI warrants performance of its semiconductor products to the specifications applicable at the time of sale in accordance with TI's standard warranty. Testing and other quality control techniques are utilized to the extent TI deems necessary to support this warranty. Specific testing of all parameters of each device is not necessarily performed, except those mandated by government requirements.

CERTAIN APPLICATIONS USING SEMICONDUCTOR PRODUCTS MAY INVOLVE POTENTIAL RISKS OF DEATH, PERSONAL INJURY, OR SEVERE PROPERTY OR ENVIRONMENTAL DAMAGE ("CRITICAL APPLICATIONS"). TI SEMICONDUCTOR PRODUCTS ARE NOT DESIGNED, AUTHORIZED, OR WARRANTED TO BE SUITABLE FOR USE IN LIFE-SUPPORT DEVICES OR SYSTEMS OR OTHER CRITICAL APPLICATIONS. INCLUSION OF TI PRODUCTS IN SUCH APPLICATIONS IS UNDERSTOOD TO BE FULLY AT THE CUSTOMER'S RISK.

In order to minimize risks associated with the customer's applications, adequate design and operating safeguards must be provided by the customer to minimize inherent or procedural hazards.

TI assumes no liability for applications assistance or customer product design. TI does not warrant or represent that any license, either express or implied, is granted under any patent right, copyright, mask work right, or other intellectual property right of TI covering or relating to any combination, machine, or process in which such semiconductor products or services might be or are used. TI's publication of information regarding any third party's products or services does not constitute TI's approval, warranty or endorsement thereof.

Copyright © 1998, Texas Instruments Incorporated

Copyright © Each Manufacturing Company.

All Datasheets cannot be modified without permission.

This datasheet has been download from :

www.AllDataSheet.com

100% Free DataSheet Search Site.

Free Download.

No Register.

Fast Search System.

www.AllDataSheet.com